

Forum

Driving Innovation through Collaboration between Devices and Applications

This forum serves as a platform to drive innovation and create new value through the integration of semiconductor technology and applications. To accelerate innovation, it is crucial to share challenges and collaborate from the perspectives of both devices and applications. By addressing these challenges and fostering deeper collaboration, this forum aims to unlock new possibilities.

2025.10.22 Wed 13:00–15:50 (JST)

TKP GardenCity PREMIUM Sendai Nishiguchi, Hall 5C, Sendai, Japan

Program

● 13:00	Opening Remarks	Toshiyuki Mitsue Deloitte Tohmatsu Consulting	
● 13:05	Advancing Semiconductor Development in Tohoku: Current Initiatives and Future Plans	Takamitsu Imoto Tohoku Bureau of Economy, Trade and Industry	
● 13:35	Non-Technical Challenges in the Electronic Device Industry and the Role of Academia	Shuji Tanaka Tohoku University	
● 14:05	Shaping Device Innovation through Application Collaboration: A Case Study on Secure Computation	Yoshihiro Ohba EmotionX	
● 14:35	Break		
● 14:45	Creating Value through Synergy between Devices and Applications	Motoshi Mineo Macnica, Inc.	
● 15:15	Panel Discussions	Panelists : The above speakers	
● 15:50	Closing		